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SEP 17 2007

Application No.: 10/810,436

Docket No.: JCLA12013-R

REMARKSPresent Status of the Application

Claims 1, 3-7 were rejected under 35 U.S.C. 103(a) as being unpatentable over Martin (US 6,323,550 B1; hereinafter Martin) in view of Meckes (US 7,061,098; hereafter Meckes). Claim 8 was rejected under 35 U.S.C. 103(a) as being unpatentable over Martin in view of Meckes and Nishiguchi (JP 04024928; hereafter Nishiguchi).

Claim 1 has been amended for clarification purposes. Supporting grounds can be found at least in figure 1A-1C. No new matter has been added to the application by the amendments made to the specification, claims and drawings. After carefully considering the remarks set forth in this Office Action and the cited references, Applicants respectfully submitted that the presently pending claims are in condition for allowance. Reconsideration and withdrawal of the Examiner's rejection are requested.

Discussion of the claim rejection under 35 USC 103

*Claims 1, 3-7 were rejected under 35 U.S.C. 103(a) as being unpatentable over Martin in view of Meckes.*

Applicants respectfully submit that Martin in view of Meches is legally deficient to render claim 1 unpatentable. Also, Applicants respectfully traverse this rejection but have amended claim 1 to clearly define the chip package according to the invention. As amended, claim 1 recites:

Claim 1. A chip package, for disposing on a printed circuit board (PCB),

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the chip package comprising:

a chip, having an active surface and a plurality of bond pads, said bond pads being on said active surface;

a rigid cover, on said active surface, said rigid cover exposing said plurality of bond pads above said active surface, wherein the rigid cover is located between the chip and the PCB;

an adhesive layer, disposed between the chip and the rigid cover, and the rigid cover is adhered to the chip via the adhesive layer; and

a plurality of contacts, electrically connected to said plurality of bond pads respectively, wherein the contacts are conductive bumps, and the contacts are connected to the PCB.

In the present application, the bond pads 114 are connected to PCB 140 via the contacts such as conductive bumps [para. 29, lines 3-6, Fig. 1C] and the rigid cover 120 is disposed between the chip 110 and the PCB 140 [Fig. 1C]. That is, the chip electrically connected to the PCB in a manner of that the active surface of the chip faces the PCB. However, Martin disclosed that the chip 10 and the leadframe 20 are disposed at the same horizontal level while the chip 10 and the leadframe 20 are electrically connected to each other through the wirebonds 18 and the ballbonds 16 [column 4, lines 14-16, Fig. 4]. Although Meckes discloses an electric component 1 with bump type contacts 14, Martin fails to teach or suggest that the leadframe style package can be changed to a flip-chip style package by using the bumps to connect the chip to the carrier. Also, neither Martin nor Meches teaches or suggests the chip with the ballbonds

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is disposed to be upside down so that the silicon cap 50 on the chip 10 faces the PCB as recited in the amended claim 1.

Applicants respectfully submit that, as disclosed above, independent claim 1 patently distinguishes over the prior art references, and should be allowed. For at least the same reasons, dependent claims 3-7 patently define over the prior art as a matter of law, for at least the reason that these dependent claims contain all features of their respective independent claim. Reconsideration and withdrawal of these 103 rejections are respectfully requested.

*Claim 8 was rejected under 35 U.S.C. 103(a) as being unpatentable over Martin in view of Meckes and Nishiguchi (JP 04024928; hereafter Nishiguchi).*

Since claim 8 is dependent claim which further defines the invention recited in claim 1, Applicants respectfully assert that this claim also is in condition for allowance according to the same reasons as discussed above for the rejection 103. Thus, reconsideration and withdrawal of this rejection are respectfully requested.

For at least the foregoing reasons, Applicants respectfully submit that independent claim 1 patently defines over the prior art references, and should be allowed. For at least the same reasons, dependent claims 3-8 patently define over the prior art as well.

#### **Newly Added Claims**

Applicants have added claim 24 for further limiting the present invention by introducing that the bond pads are arranged on the active surface in a manner of an array and the rigid cover has several openings corresponding to the bond pads and exposing the bond pads respectively

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[para. 30 and para. 31 Fig. 2A]. It is believed that no new matter is introduced into the application by adding the new set of claims.

Neither Martin nor Meckes teaches or suggests that the silicon cap 50 in Martin's application possesses openings to expose the bond pads located on the active surface. Apparently, the combination of cited arts does not render claim 24 unpatentable.

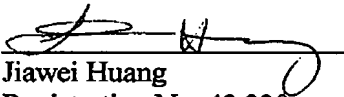
### CONCLUSION

In view of the foregoing, it is believed that all pending claims are in proper condition for allowance. If the Examiner believes that a conference would be of value in expediting the prosecution of this application, he is cordially invited to telephone the undersigned counsel to arrange for such a conference.

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Respectfully submitted,  
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